## BAS216W-AH

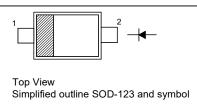
# Silicon Epitaxial Planar Switching Diode

### **Features**

- AEC-Q101 Qualified
- Halogen and Antimony Free(HAF), RoHS compliant

#### PINNING

PIN	DESCRIPTION		
1	Cathode		
2	Anode		



## Absolute Maximum Ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit	
Repetitive Peak Reverse Voltage		$V_{RRM}$	85	V
Reverse Voltage		$V_R$	75	V
Continuous Forward Current	I <sub>F</sub>	250	mA	
Repetitive Peak Forward Current		I <sub>FRM</sub>	500	mA
Non-repetitive Peak Forward Surge Current	at t = 1 s at t = 1 ms at t = 1 µs	I <sub>FSM</sub>	0.5 1 4	А
Power Dissipation		P <sub>tot</sub>	400	mW
Junction Temperature		T <sub>j</sub>	150	°C
Storage Temperature Range		$T_{stg}$	- 65 to + 150	°C

### **Thermal Characteristics**

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient 1)	$R_{ heta JA}$	313	°C/W

<sup>&</sup>lt;sup>1)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# BAS216W-AH

## Characteristics at T<sub>a</sub> = 25℃

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I <sub>R</sub> = 10 μA	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V <sub>F</sub>		0.715 0.855 1 1.25	V
Reverse Current at $V_R = 25 \text{ V}$ at $V_R = 75 \text{ V}$ at $V_R = 25 \text{ V}$ , $T_j = 150 ^{\circ}\text{C}$ at $V_R = 75 \text{ V}$ , $T_j = 150 ^{\circ}\text{C}$	I <sub>R</sub>		30 1 30 50	nΑ μΑ μΑ μΑ
Diode Capacitance at $V_R = 0 V$ , $f = 1 MHz$	C <sub>tot</sub>	-	1.5	pF
Reverse Recovery Time at $I_F$ = 10 mA, $I_{rr}$ = 0.1 X $I_R$ , $V_R$ = 6 V, $R_L$ = 100 $\Omega$	t <sub>rr</sub>	-	4	ns



### **Electrical Characteristics Curves**

Fig 1. Power Derating Curve

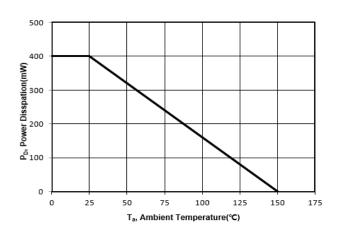


Fig 2. Capacitance Characteristics

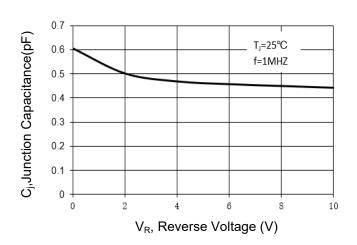


Fig 3. Reverse Characteristics

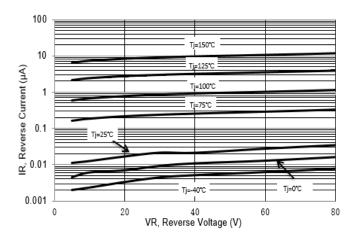
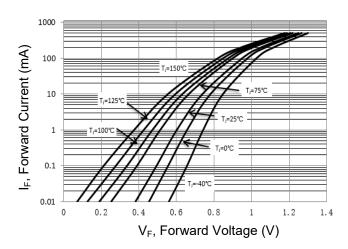


Fig 4. Forward Characteristics

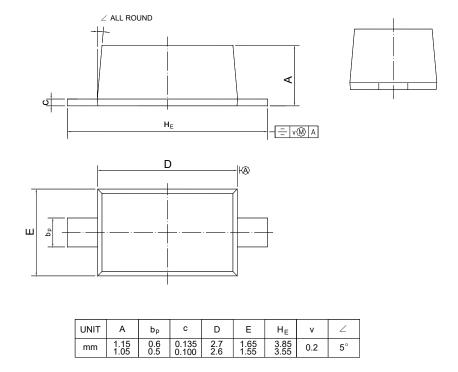




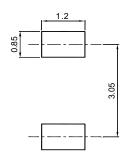
### **PACKAGE OUTLINE**

### Plastic surface mounted package; 2 leads

**SOD-123** 



## **Recommended Soldering Footprint**



### **Packing information**

Package Tape Width		Pitch		Reel	Size	Per Reel Packing Quantity
Fackage	(mm)	mm	(inch)	mm	(inch)	rei Neel Fackling Quantity
SOD-123	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

## **Marking information**

"W1" = Part No

"III" = Cathode line

" • "= HAF (Halogen and Antimony Free(HAF)

Font type: Arial



Disclaimer: Our company reserve the right to make modifications, enhancements, improvements, corrections or other changes to improve product design, functions and reliability, anytime without notice. Semtech Electronics Limited makes no warranties, representations or warranties regarding the suitability of its products for any particular purpose, and does not accept any liability arising from the application or use of any product or circuit such as: Apply to medical, military, aircraft, space or life support equipment and expressly waive any and all liability, including but not limited to special, consequential or collateral damage.

